

Chip Scale Review

2016 Editorial Calendar

(Editorial close date: 11/20)

January • February

(* denotes show distribution)

Packaging trends	<ul style="list-style-type: none"> • SEMI European 3D Summit Grenoble, France (Jan 18-20) * • SMTA Pan Pac Microelectronics Symposium * Kohala Coast, Hawaii (Jan 25-28) • SEMICON Korea Seoul, Korea (January 27-29) • BiTS Workshop * Mesa, AZ (March 6-9) • APEX Expo Las Vegas, NV (March 15-17) • IMAPS Device Packaging (DPC) * Fountain Hills, AZ (March 15-17) • SEMICON China* Productronica China Shanghai China (March 15-17)
Assembly materials	
Cu TSV stress analysis	
Wafer carrier solutions	
Recent advances in 3D package reliability	
Metrology for 3D integration	
Silicon photonics packaging	
Advances in wafer probing	
Socket contact technologies	

International Directory of Test and Burn-in Socket Suppliers

Ad Space Close Jan 22 - Ad Materials Deadline Jan 29

(Editorial close date: 2/5)

March • April

MEMS in IoT devices	<ul style="list-style-type: none"> • SEMICON South East Asia Penang, Malaysia (Apr 26-28) • MEPTEC MEMS Symposium * San Jose, CA (May 11) • ECTC * Las Vegas, NV (May 31- June 3)
Copper Pillar Technology	
FOWLP	
Die-to-wafer stacking	
Flexible substrates	
Packaging of high-power devices	
3D integration in packaging	
Lithography for TSVs	
TSV technologies	

Ad Space Close Feb 19 - Materials Close Feb 26

(Editorial close date: 3/11)

May • June

Packaging trends & update	<ul style="list-style-type: none"> • IEEE/SW Test Workshop (SWTW) San Diego, CA (June 5-8) • Sensors Expo San Jose, CA (June 21-23) • SEMICON West * San Francisco, CA (July 12-14)
Impact of wafer-based packaging on the supply chain	
FOWLP advances	
Improving yield & reliability in AOI	
Final test solution for WLCSP devices	
Multi-die assembled packages	
3D backside processing	
Emerging automotive applications	
Current state & evolving trends in MEMS packaging	

Ad Space Close May 20 - Ad Materials Close May 27